

PATENT ASSIGNMENT

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Fujio MASUOKA	09/03/2010
Shintaro ARAI	09/03/2010
Hiroki NAKAMURA	09/03/2010
Tomohiko KUDO	09/03/2010
B. Ramana MURTHY	08/19/2010
Nansheng SHEN	08/20/2010
Kavitha Devi BUDDHARAJU	08/20/2010
Navab SINGH	08/20/2010

RECEIVING PARTY DATA

Name:	Unisantis Electronics (Japan) Ltd.
Street Address:	2nd Floor, Fuji-light Shinkawa Building,
Internal Address:	22-11, Shinkawa 1-chome, Chuo-ku,
City:	Tokyo
State/Country:	JAPAN
Postal Code:	104-0033

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12858840

CORRESPONDENCE DATA

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OP \$40.00 12858840

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NAME OF SUBMITTER:

Daniel P. Lent

Total Attachments: 3

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ASSIGNMENT

WHEREAS We, **Fujio MASUOKA** of c/o Unisantis Electronics (Japan) Ltd., 2nd Floor, Fuji-light Shinkawa Building, 22-11, Shinkawa 1-chome, Chuo-ku, Tokyo 104-0033, Japan, **Shintaro ARAI** of c/o Unisantis Electronics (Japan) Ltd., 2nd Floor, Fuji-light Shinkawa Building, 22-11, Shinkawa 1-chome, Chuo-ku, Tokyo 104-0033, Japan, **Hiroki NAKAMURA** of c/o Unisantis Electronics (Japan) Ltd., 2nd Floor, Fuji-light Shinkawa Building, 22-11, Shinkawa 1-chome, Chuo-ku, Tokyo 104-0033, Japan, **Tomohiko KUDO** of c/o Unisantis Electronics (Japan) Ltd., 2nd Floor, Fuji-light Shinkawa Building, 22-11, Shinkawa 1-chome, Chuo-ku, Tokyo 104-0033, Japan, **B. Ramana MURTHY** of c/o Institute of Microelectronics, 11, Science Park Road, Singapore Science Park II, Singapore 117685, **Nansheng SHEN** of c/o Institute of Microelectronics, 11, Science Park Road, Singapore Science Park II, Singapore 117685, **Kavitha Devi BUDDHARAJU** of c/o Institute of Microelectronics, 11, Science Park Road, Singapore Science Park II, Singapore 117685 and **Navab SINGH** of c/o Institute of Microelectronics, 11, Science Park Road, Singapore Science Park II, Singapore 117685 (hereinafter referred to as "ASSIGNORS") have invented certain new and useful improvements in:

SEMICONDUCTOR DEVICE AND PRODUCTION METHOD THEREOF

which claims priority to **Japanese** Application No. 2009-189262, filed on August 18, 2009, and **U.S. Provisional** Application No. 61/274,733 filed on August 19, 2009, and for which We are about to file or have filed an application for Letters Patent of the United States;

AND WHEREAS, **Unisantis Electronics (Japan) Ltd.** (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of **Japan**, having a place of business at **2nd Floor, Fuji-light Shinkawa Building, 22-11, Shinkawa 1-chome, Chuo-ku, Tokyo 104-0033, Japan**, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date: September 3, 2010

Fujio Masuoka L.S.
Fujio MASUOKA

Date: September 3, 2010

Shintaro Arai L.S.
Shintaro ARAI


Date: September 3, 2010

Hiroki Nakamura L.S.
Hiroki NAKAMURA

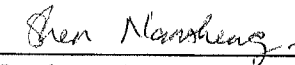
Date: September 3, 2010

Tomohiko Kudo L.S.
Tomohiko KUDO

Date: 19/08/10

 L.S.
B. Ramana MURTHY

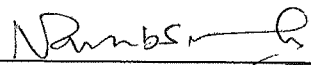
Date: August 20, 2010

 L.S.
Nansheng SHEN

Date: August 20, 2010

 L.S.
Kavitha Devi BUDDHARAJU

Date: August 20, 2010

 L.S.
Navab SINGH